

	L #	Hits	Search Text	DBs
1	L1	2882	eutectic near3 solder	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
2	L2	481	438/108.ccls.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
3	L3	14216	(gap adj fill\$4) or gapfill\$4 or (under adj fill\$4) or underfill\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
4	L4	124853	438/\$.ccls.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
5	L5	124372	4 not 2	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B

	L #	Hits	Search Text	DBs
6	L6	1306	3 and 5	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
7	L7	140199	encapsul\$5	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
8	L8	279	6 and 7	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
9	L9	398	438/122.ccls.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
10	L10	13331	flipchip or (flip adj chip)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B

	L #	Hits	Search Text	DBs
11	L11	63	9 and 10	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B
12	L12	335	9 not 11	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B